

ABSTRACT OF THE DISCLOSURE

A wiring board that allows the high-density connection with a plurality of circuit boards within a limited area, a manufacturing method for the same and electronic equipment using the same are provided. A wiring
5 board includes: a plurality of conductive layers each including one or more wirings for transmitting signals; and a plurality of insulation layers for insulating the respective conductive layers. The conductive layers and the insulation layers are laminated alternately, and each of the plurality of conductive layers is provided with a terminal at at least one of both ends.
10 The terminals are formed stepwise and separated by the insulation layers in a cross-sectional shape of a lamination structure of the conductive layers and the insulation layers.